

**N-Ch MOSFET** 

## **General Description**

The WSK250N03 is the highest performance trench N-ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSK250N03 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### **Product Summery**

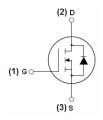
BVDSS	RDSON	ID
30V	1.8mΩ	250A

# **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System

# **TO-263-2L Pin Configuration**





# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
$V_{DS}$	Drain-Source Voltage	30	V	
$V_{GS}$	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	250	Α	
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	180	Α	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	1000	Α	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	600	mJ	
I <sub>AS</sub>	Avalanche Current	200	А	
P <b></b> _@T <sub>C</sub> =25℃	Total Power Dissipation <sup>3</sup>	200	W	
P <sub>D</sub> @T <sub>C</sub> =100℃	Total Power Dissipation <sup>3</sup>	120	W	
T <sub>STG</sub>	Storage Temperature Range	-55 to 170	$^{\circ}\!\mathbb{C}$	
$T_J$	Operating Junction Temperature Range	-55 to 175	$^{\circ}\!\mathbb{C}$	



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.098		V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}$ =10V , $I_D$ =20A		1.8	2.5	mΩ
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		2.5	3.5	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1	1.8	3	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient			-6.57		mV/℃
	Drain Source Leakage Current	V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	uA
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =80V , $V_{GS}$ =0V , $T_J$ =55 $^{\circ}$ C			2	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =20A	28			S
$Q_g$	Total Gate Charge (10V)			232		
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =50V , V <sub>GS</sub> =10V , I <sub>D</sub> =120A		26		nC
Q <sub>gd</sub>	Gate-Drain Charge			59		
T <sub>d(on)</sub>	Turn-On Delay Time			50		
T <sub>r</sub>	Rise Time	V <sub>DD</sub> =30V , V <sub>GS</sub> =10V ,		111		20
T <sub>d(off)</sub>	Turn-Off Delay Time	$R_G=6\Omega I_D=145A$ ,		88		ns
T <sub>f</sub>	Fall Time	RL=30Ω		74		
C <sub>iss</sub>	Input Capacitance			10600		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , f=1MHz		1156		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			732		

# **Diode Characteristics**

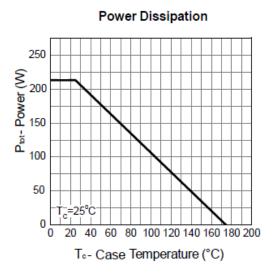
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			250	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				300	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}$ =0V , $I_{S}$ =20A , $T_{J}$ =25 $^{\circ}$ C			1.2	V

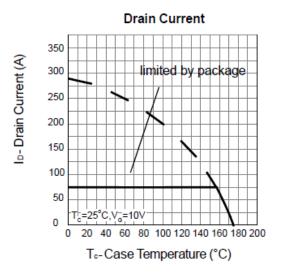
#### Note

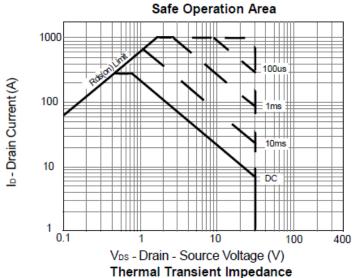
- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t≤10sec.
- 2.The data tested by pulsed , pulse width  $\,\leq\,300\text{us}$  , duty cycle  $\,\leq\,2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V, $V_{GS}$ =10V,L=0.5mH, $I_{AS}$ =20A
- 4.The power dissipation is limited by 150 ℃ junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

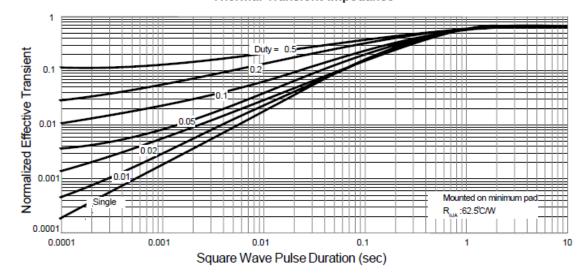
**N-Ch MOSFET** 

# **Typical Characteristics**



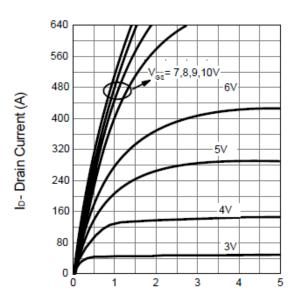






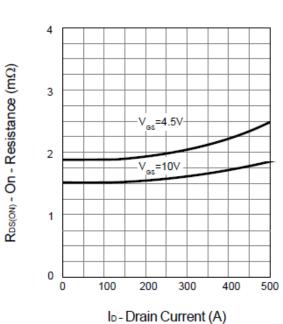




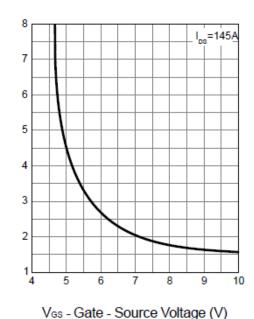


V<sub>DS</sub> - Drain-Source Voltage (V)

### Drain-Source On Resistance

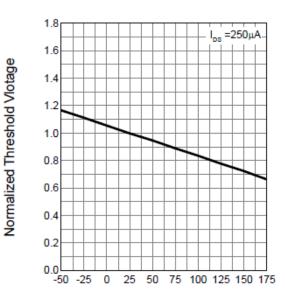


Drain-Source On Resistance



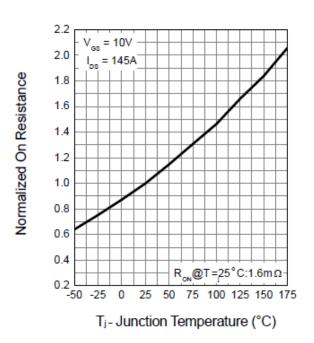
RDS(ON) - On - Resistance (mΩ)

Gate Threshold Voltage

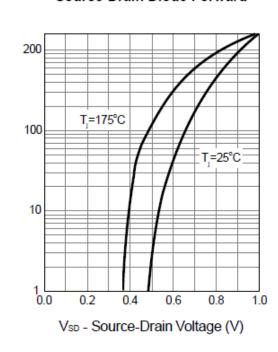




### **Drain-Source On Resistance**



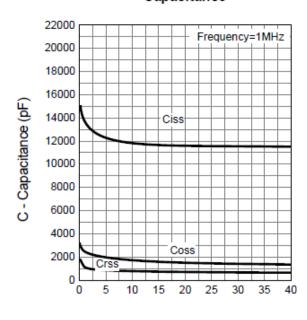
#### Source-Drain Diode Forward



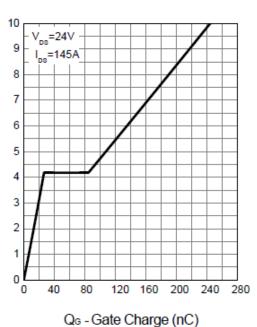
Is - Source Current (A)

Vos - Gate-source Voltage (V)

### Capacitance



Gate Charge



V<sub>DS</sub> - Drain - Source Voltage (V)



# Package Information

UNIT: mm 10.0 TYP. 4.8 MAX. 1,0±0,5 1.3±0.2 8.540.2 1.6 MAX. 2.54±0.25 5.7±0.4 0.7±0.2 0.5±0.2 1.4±0.2 2.54 TYP. 2.54 TYP. 2.840.2

TO-263-2L



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